



SML-01* Serise

Surface Mount Chip LEDs

This product was developed as a surface mount LED especially suitable for soldering. Please take care of following points when using this device.

1. DESIGNING OF PCB

As for a recommendable solder pattern, Please refer to Fig-1.

The size and direction of the pad pattern depends on the condition of the PCB, So, please investigate about the adjustment thoroughly before designing.

2. MOUNTING

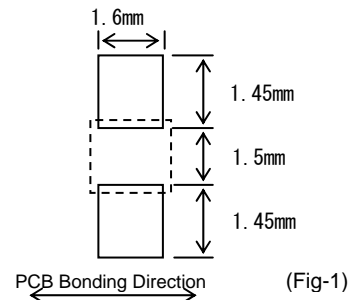
This LED was designed to fit various mounting machines. A round type nozzle is recommended for a hollow lens surface.

3. SOLDERING

LED products do not contain reinforcement materials such as glass fillers. Therefore, thermal stress by soldering greatly influences its reliability.

The temperature condition for reflow soldering should therefore be set up according to the characteristic of this products. (See Fig.2)

Number of reflow process shall be max 2 times and these process shall be performed in a row. Cooling process to normal temp. Shall be required between first and second soldering process.



(Fig-1)

4. WASHING

Please note the following points when washing is required after soldering.

4-1) WASHING SOLVENT

Isopropyl alcohol or other alcohol solvent is recommendable.

4-2) TEMPERATURE

Below 30°C, immersion time ; within 3 minutes.

4-3) ULTRA SONIC WASHING

Below 15 / 1 litter of solvent tub.

4-4) CULING

Below 100°C within 3 minutes.

5. STRAGE

At reflow soldering, the reliability of this product is often influenced by moisture absorption so we apply the packaging with moistureproof for better condition is use, please also note that

5-1) Not to be opened before using.

5-2) To be kept in our moistureproof packaging with some desiccant (SILICA GEL) after opening it. To be baked in case the SILICA GEL indicator loses its blue color.

5-3) Please use within 168 hours after the package was opened. (Condition at 30°C, max.70%Rh.)

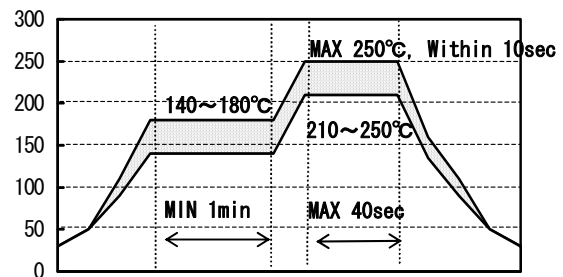
In case it is not used within 168 hours, please put it back into our packaging.

5-4) BAKING

Please bake under reel condition at 60°C, 12~24 hours (max.20%Rh) after un-sealing.

While baking is done, the reel and emboss tape may be easily deformed.

Please be careful not to give any stress.



(Fig-2)